

## SNx4AHCT32 Quadruple 2-Input Positive-OR Gates

### 1 Features

- Inputs are TTL-voltage compatible
- Latch-up performance exceeds 250 mA per JESD 17
- ESD protection exceeds JESD 22
  - 2000-V Human-Body Model
  - 200-V Machine Model
- On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters

### 2 Applications

- Electronic points-of-sale
- Telecom infrastructure
- Network switches
- Test and measurement

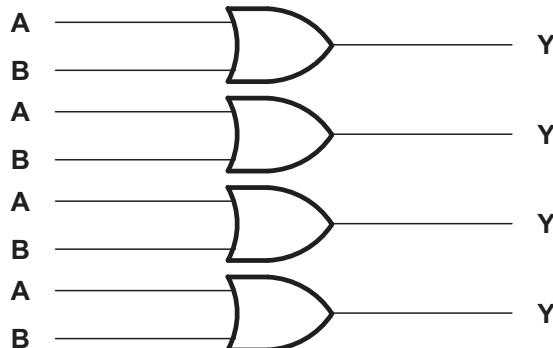
### 3 Description

The SNx4AHCT32 devices are quadruple 2-input positive-OR gates. These devices perform the Boolean function  $Y = \overline{A} \times \overline{B}$  or  $Y = A + B$  in positive logic.

#### Package Information<sup>(1)</sup>

PART NUMBER	PACKAGE	BODY SIZE (NOM)
SN54AHCT32	J (CDIP, 14)	19.56 mm × 6.67 mm
	W (CFP, 14)	13.09 mm × 6.92 mm
	FK (LCCC, 20)	8.89 mm × 8.89 mm
SN74AHCT32	N (PDIP, 14)	19.3 mm × 6.35 mm
	D (SOIC, 14)	8.65 mm × 3.91 mm
	NS (SOP, 14)	10.30 mm × 5.30 mm
	DB (SSOP, 14)	6.20 mm × 5.30 mm
	PW (TSSOP, 14)	5.00 mm × 4.40 mm
	DGV (TFSOP, 14)	3.60 mm × 4.40 mm
	RGY (VQFN, 14)	3.50 mm × 3.50 mm
	BQA (WQFN, 14)	3.00 mm × 2.50 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.



Simplified Schematic



An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.

## Table of Contents

<b>1 Features</b> .....	<b>1</b>	8.1 Overview.....	<b>8</b>
<b>2 Applications</b> .....	<b>1</b>	8.2 Functional Block Diagram.....	<b>8</b>
<b>3 Description</b> .....	<b>1</b>	8.3 Feature Description.....	<b>8</b>
<b>4 Revision History</b> .....	<b>2</b>	8.4 Device Functional Modes.....	<b>8</b>
<b>5 Pin Configuration and Functions</b> .....	<b>3</b>	<b>9 Application and Implementation</b> .....	<b>9</b>
<b>6 Specifications</b> .....	<b>4</b>	9.1 Application Information.....	<b>9</b>
6.1 Absolute Maximum Ratings.....	4	9.2 Typical Application.....	<b>9</b>
6.2 ESD Ratings.....	4	9.3 Power Supply Recommendations.....	<b>10</b>
6.3 Recommended Operating Conditions.....	4	9.4 Layout.....	<b>10</b>
6.4 Thermal Information.....	5	<b>10 Device and Documentation Support</b> .....	<b>11</b>
6.5 Electrical Characteristics.....	5	10.1 Receiving Notification of Documentation Updates..	<b>11</b>
6.6 Switching Characteristics.....	5	10.2 Support Resources.....	<b>11</b>
6.7 Noise Characteristics.....	6	10.3 Trademarks.....	<b>11</b>
6.8 Operating Characteristics.....	6	10.4 Electrostatic Discharge Caution.....	<b>11</b>
6.9 Typical Characteristics.....	6	10.5 Glossary.....	<b>11</b>
<b>7 Parameter Measurement Information</b> .....	<b>7</b>	<b>11 Mechanical, Packaging, and Orderable</b> <b>Information</b> .....	<b>11</b>
<b>8 Detailed Description</b> .....	<b>8</b>		

## 4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

<b>Changes from Revision N (May 2023) to Revision O (July 2023)</b>	<b>Page</b>
• Updated thermal values for R <sub>0JA</sub> : PW = 125.1 to 147.7, R <sub>0JC(top)</sub> = 53.7 to 77.4, R <sub>0JB</sub> = 66.9 to 90.9, $\Psi_{JT}$ = 7.6 to 27.2, $\Psi_{JB}$ = 66.3 to 90.2, all values in °C/W.”	<b>5</b>
<hr/>	
<b>Changes from Revision M (October 2014) to Revision N (May 2023)</b>	<b>Page</b>
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	<b>1</b>
• Updated the <i>Package Information</i> table.....	<b>1</b>
• Added the <i>BQA</i> package to the data sheet.....	<b>1</b>

## 5 Pin Configuration and Functions

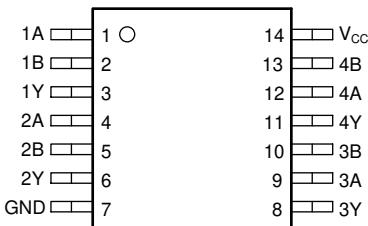


Figure 5-1. SN54AHCT32 J or W Package, 14-Pin  
(Top View)

SN74AHCT32 D, DB, DGV, N, NS, or PW Package,  
14-Pin (Top View)

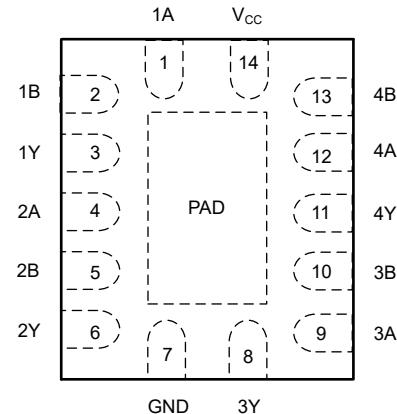


Figure 5-2. SN74AHCT32 RGY or BQA Package,  
14-Pin (Top View)

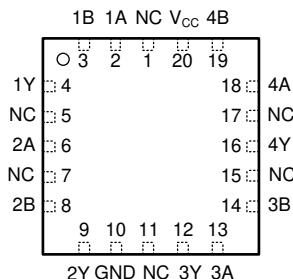


Figure 5-3. SN54AHCT32 FK Package, 20-Pin (Top View)

Table 5-1. Pin Functions

NAME	PIN				TYPE <sup>(1)</sup>	DESCRIPTION		
	SN74AHCT32		SN54AHCT32					
	D, DB, DGV, N, NS, PW	RGY, BQA	J, W	FK				
1A	1	1	1	2	I	1A Input		
1B	2	2	2	3	I	1B Input		
1Y	3	3	3	4	O	1Y Output		
2A	4	4	4	6	I	2A Input		
2B	5	5	5	8	I	2B Input		
2Y	6	6	6	9	O	2Y Output		
3Y	8	8	8	12	O	3Y Output		
3A	9	9	9	13	I	3A Input		
3B	10	10	10	14	I	3B Input		
4Y	11	11	11	16	O	4Y Output		
4A	12	12	12	18	I	4A Input		
4B	13	13	13	19	I	4B Input		
GND	7	7	7	10	—	Ground Pin		
NC	—	—	—	1, 5, 7, 11, 15, 17	—	No Connection		
V <sub>CC</sub>	14	14	14	20	I	Power Pin		
Thermal Pad	—	PAD	—	—	—	Thermal Pad		

(1) I = input, O = output

## 6 Specifications

### 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) <sup>(1)</sup>

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage range	-0.5	7	V
$V_I$	Input voltage range <sup>(2)</sup>	-0.5	7	V
$V_O$	Output voltage range <sup>(2)</sup>	-0.5	$V_{CC} + 0.5$	V
$I_{IK}$	Input clamp current	$V_I < 0$	-20	mA
$I_{OK}$	Output clamp current	$V_O < 0$ or $V_O > V_{CC}$	$\pm 20$	mA
$I_O$	Continuous output current	$V_O = 0$ to $V_{CC}$	$\pm 25$	mA
	Continuous current through $V_{CC}$ or GND		$\pm 50$	mA
$T_{stg}$	Storage temperature range	-65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

### 6.2 ESD Ratings

		VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM)	$\pm 1000$
		Charged device model (CDM)	

### 6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted) <sup>(1)</sup>

		SN54AHCT32		SN74AHCT32		UNIT
		MIN	MAX	MIN	MAX	
$V_{CC}$	Supply voltage	4.5	5.5	4.5	5.5	V
$V_{IH}$	High-level input voltage	2		2		V
$V_{IL}$	Low-level input voltage		0.8		0.8	V
$V_I$	Input voltage	0	5.5	0	5.5	V
$V_O$	Output voltage	0	$V_{CC}$	0	$V_{CC}$	V
$I_{OH}$	High-level output current		-8		-8	mA
$I_{OL}$	Low-level output current		8		8	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		20		20	ns/V
$T_A$	Operating free-air temperature	-55	125	-40	125	°C

(1) All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs* ([SCBA004](#)).

## 6.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		SN74AHCT32								UNIT °C/W
		D	DB	DGV	N	NS	PW	RGY	BQA	
		14 PINS								
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	97.5	109.5	133.3	59.7	92.2	147.7	59.0	88.3	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	58.7	62.1	55.6	47.3	49.8	77.4	72.5	90.9	
R <sub>θJB</sub>	Junction-to-board thermal resistance	51.8	56.9	66.3	39.5	51.0	90.9	35.0	56.8	
Ψ <sub>JT</sub>	Junction-to-top characterization parameter	22.6	22.6	7.8	32.4	15.7	27.2	3.9	9.9	
Ψ <sub>JB</sub>	Junction-to-board characterization parameter	51.6	56.3	56.6	39.4	50.6	90.2	35.1	56.7	
R <sub>θJC(bot)</sub>	Junction-to-case (bottom) thermal resistance	—	—	—	—	—	—	15.4	33.4	

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report (SPRA953).

## 6.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			SN54AHCT32		SN74AHCT32		-40°C to 125°C SN74AHCT32		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
V <sub>OH</sub>	I <sub>OH</sub> = -50 µA	4.5 V	4.4	4.5	—	4.4	—	4.4	—	4.4	—	V
	I <sub>OH</sub> = -8 mA		3.94	—	—	3.8	—	3.8	—	3.8	—	
V <sub>OL</sub>	I <sub>OL</sub> = 50 µA	4.5 V	—	0.1	—	0.1	—	0.1	—	0.1	—	V
	I <sub>OL</sub> = 8 mA		—	0.36	—	0.44	—	0.44	—	0.44	—	
I <sub>I</sub>	V <sub>I</sub> = 5.5 V or GND	0 V to 5.5 V	—	±0.1	—	±1 <sup>(1)</sup>	—	±1	—	±1	—	µA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	5.5 V	—	2	—	20	—	20	—	20	—	µA
ΔI <sub>CC</sub> <sup>(2)</sup>	One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND	5.5 V	—	1.35	—	1.5	—	1.5	—	1.5	—	mA
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	5 V	2	10	—	10	—	10	—	10	—	pF

(1) On products compliant to MIL-PRF-38535, this parameter is not production tested at V<sub>CC</sub> = 0 V.

(2) This is the increase in supply current for each input at one of the specified TTL voltage levels, rather than 0 V or V<sub>CC</sub>.

## 6.6 Switching Characteristics

over recommended operating free-air temperature range, V<sub>CC</sub> = 5 V ± 0.5 V (unless otherwise noted) (see Figure 7-1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T <sub>A</sub> = 25°C		SN54AHCT32		SN74AHCT32		-40°C to 125°C SN74AHCT32		UNIT
				TYP	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A or B	Y	C <sub>L</sub> = 15 pF	5 <sup>(1)</sup>	6.9 <sup>(1)</sup>	1 <sup>(1)</sup>	8 <sup>(1)</sup>	1	8	1	9	ns
				5 <sup>(1)</sup>	6.9 <sup>(1)</sup>	1 <sup>(1)</sup>	8 <sup>(1)</sup>	1	8	1	9	
t <sub>PLH</sub>	A or B	Y	C <sub>L</sub> = 50 pF	5.5	7.9	1	9	1	9	1	10	ns
				5.5	7.9	1	9	1	9	1	10	

(1) On products compliant to MIL-PRF-38535, this parameter is not production tested.

## 6.7 Noise Characteristics

$V_{CC} = 5$  V,  $C_L = 50$  pF,  $T_A = 25^\circ\text{C}$ <sup>(1)</sup>

PARAMETER	SN74AHCT32			UNIT
	MIN	TYP	MAX	
$V_{OL(P)}$ Quiet output, maximum dynamic $V_{OL}$		0.4	0.8	V
$V_{OL(V)}$ Quiet output, minimum dynamic $V_{OL}$		-0.4	-0.8	V
$V_{OH(V)}$ Quiet output, minimum dynamic $V_{OH}$			4.5	V
$V_{IH(D)}$ High-level dynamic input voltage		2		V
$V_{IL(D)}$ Low-level dynamic input voltage			0.8	V

(1) Characteristics are for surface-mount packages only.

## 6.8 Operating Characteristics

$V_{CC} = 5$  V,  $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
$C_{pd}$ Power dissipation capacitance	No load, $f = 1$ MHz	11.5	pF

## 6.9 Typical Characteristics

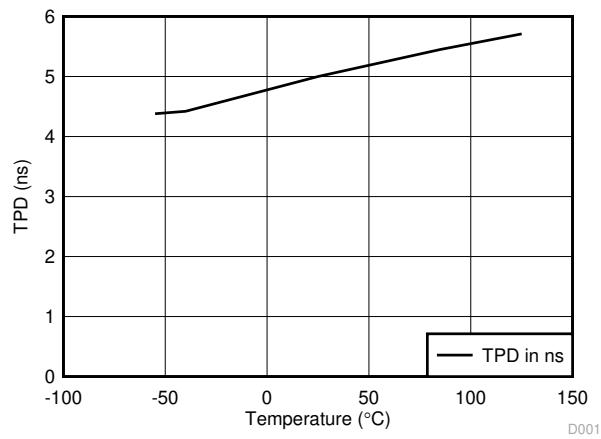
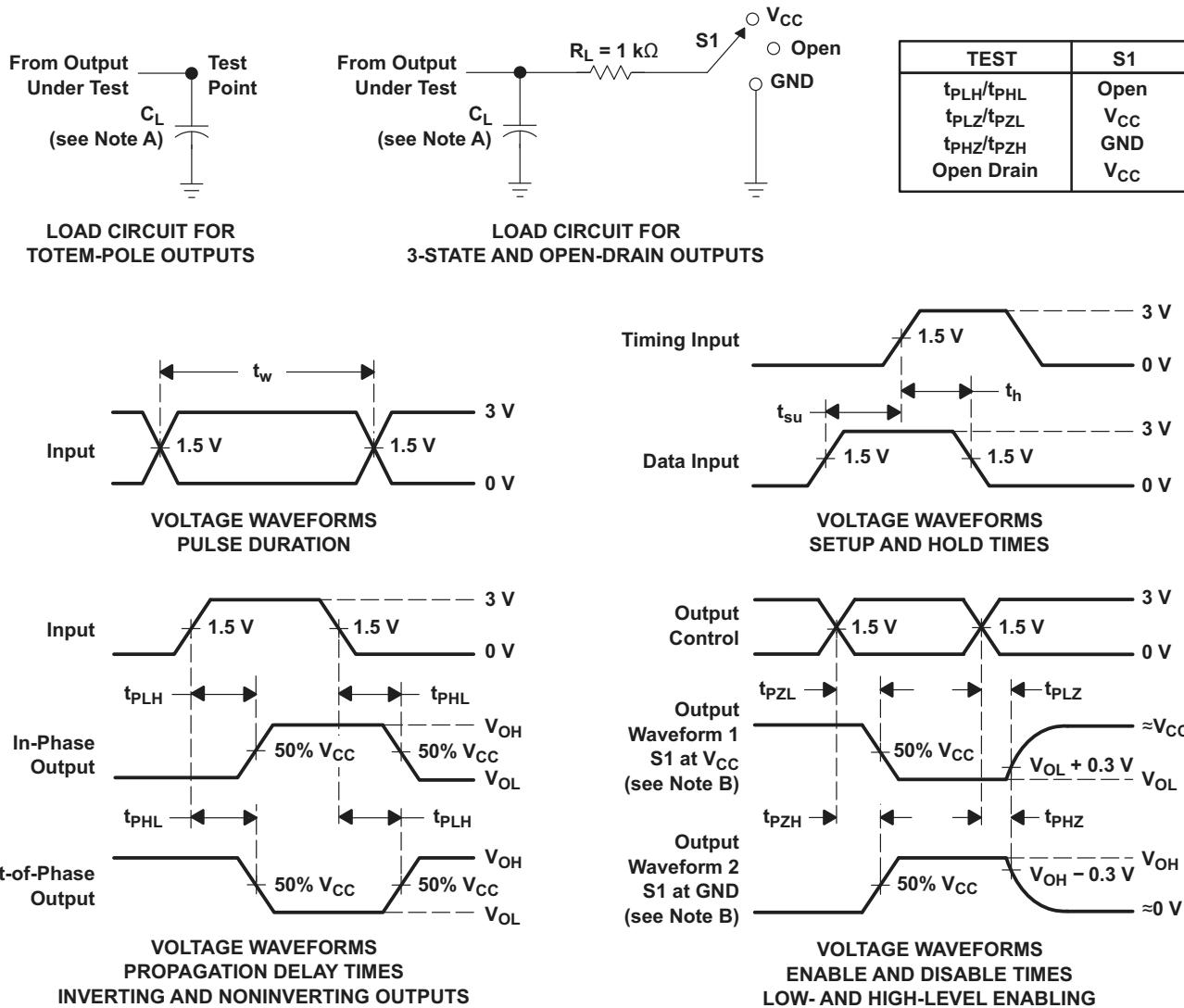


Figure 6-1. TPD vs Temperature

## 7 Parameter Measurement Information



NOTES:

- $C_L$  includes probe and jig capacitance.
- Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r \leq 3 \text{ ns}$ ,  $t_f \leq 3 \text{ ns}$ .
- The outputs are measured one at a time with one input transition per measurement.
- All parameters and waveforms are not applicable to all devices.

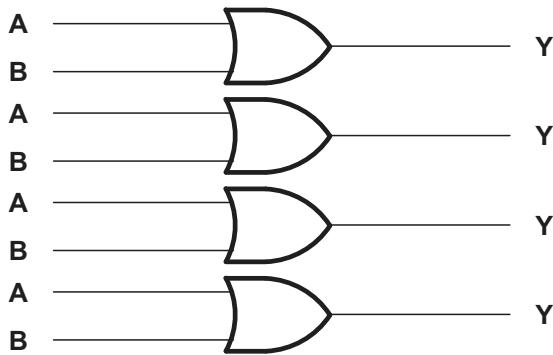
Figure 7-1. Load Circuit and Voltage Waveforms

## 8 Detailed Description

### 8.1 Overview

The SNx4AHCT32 is a quadruple 2-input positive-OR gate with low drive that will produce slow rise and fall times. This slow transition reduces ringing on the output signal. The device has TTL inputs that allow up translation from 3.3 V to 5 V. The inputs are high impedance when  $V_{CC} = 0$  V.

### 8.2 Functional Block Diagram



### 8.3 Feature Description

- Slow rise and fall time on outputs allows for low-noise outputs
- TTL inputs allow up translation from 3.3 V to 5 V

### 8.4 Device Functional Modes

**Table 8-1. Function Table  
(Each Gate)**

INPUTS		OUTPUT Y
A	B	
H	X	H
X	H	H
L	L	L

## 9 Application and Implementation

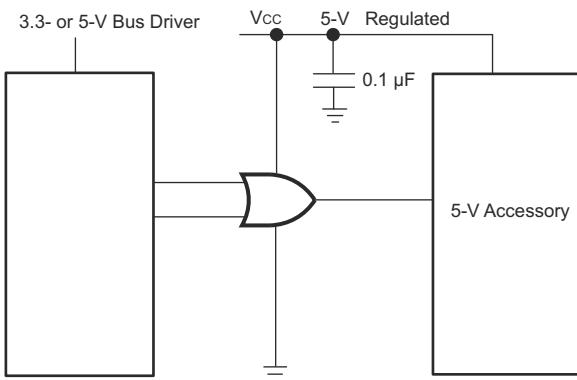
### Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

### 9.1 Application Information

The SNx4AHCT32 is a low-drive CMOS device that can be used for a multitude of bus-interface type applications where output ringing is a concern. The low drive and slow edge rates will minimize overshoot and undershoot on the outputs. The TTL inputs can accept voltages down to 3.3 V and can translate up to 5 V.

### 9.2 Typical Application



**Figure 9-1. Typical Application Diagram for a Single Gate**

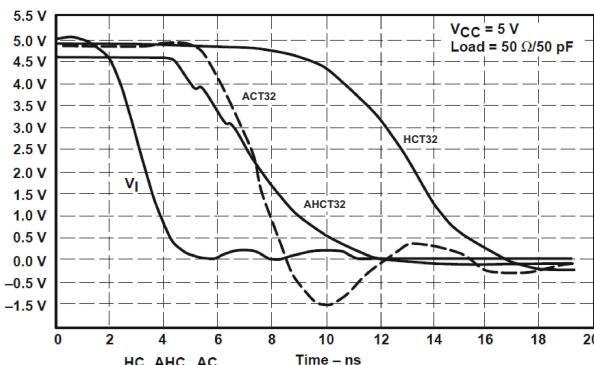
#### 9.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Care should be taken to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads, so routing and load conditions should be considered to prevent ringing.

#### 9.2.2 Detailed Design Procedure

1. Recommended input conditions:
  - For rise time and fall time specifications, see  $\Delta t/\Delta V$  in the [Recommended Operating Conditions](#) table.
  - For specified high and low levels, see  $V_{IH}$  and  $V_{IL}$  in the [Recommended Operating Conditions](#) table.
  - Inputs are overvoltage tolerant allowing them to go as high as 5.5 V at any valid  $V_{CC}$ .
2. Recommend output conditions:
  - Load currents should not exceed 25 mA per output and 50 mA total for the part.
  - Outputs should not be pulled above  $V_{CC}$ .

### 9.2.3 Application Curves



**Figure 9-2. Switching Characteristics Comparison**

## 9.3 Power Supply Recommendations

The power supply can be any voltage between the MIN and MAX supply-voltage rating located in *Recommended Operating Conditions*.

Each  $V_{CC}$  pin should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, 0.1  $\mu$ F is recommended. If there are multiple  $V_{CC}$  pins then a 0.01  $\mu$ F or a 0.022  $\mu$ F is recommended for each power pin. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. A 0.1  $\mu$ F and a 1  $\mu$ F are commonly used in parallel. The bypass capacitor should be installed as close to the power pin as possible for best results.

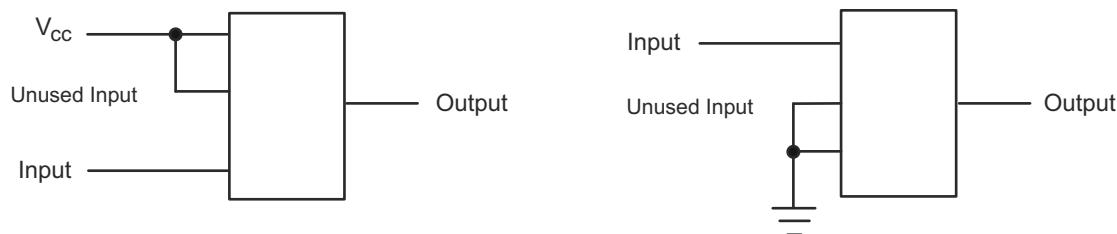
## 9.4 Layout

### 9.4.1 Layout Guidelines

When using multiple bit logic devices, inputs should never float.

In many cases, functions or parts of functions of digital logic devices are unused, for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. Figure 9-3 shows the rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or  $V_{CC}$ , whichever makes more sense or is more convenient. It is generally acceptable to float outputs, unless the part is a transceiver. If the transceiver has an output enable pin it will disable the outputs section of the part when asserted. This will not disable the input section of the I/Os so they also cannot float when disabled.

### 9.4.2 Layout Example



**Figure 9-3. Layout Diagram**

## 10 Device and Documentation Support

### 10.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](http://ti.com). Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 10.2 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

### 10.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.

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### 10.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 10.5 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

## 11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
5962-9682601Q2A	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9682601Q2A SNJ54AHCT32FK
5962-9682601QCA	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9682601QC A SNJ54AHCT32J
5962-9682601QDA	Active	Production	CFP (W)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9682601QD A SNJ54AHCT32W
SN74AHCT32BQAR	Active	Production	WQFN (BQA)   14	3000   LARGE T&R	Yes	SELECTIVE AG (TOP SIDE)	Level-1-260C-UNLIM	-40 to 125	AHCT32
SN74AHCT32BQAR.A	Active	Production	WQFN (BQA)   14	3000   LARGE T&R	Yes	SELECTIVE AG (TOP SIDE)	Level-1-260C-UNLIM	-40 to 125	AHCT32
SN74AHCT32D	Obsolete	Production	SOIC (D)   14	-	-	Call TI	Call TI	-40 to 85	AHCT32
SN74AHCT32DBR	Active	Production	SSOP (DB)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HB32
SN74AHCT32DBR.A	Active	Production	SSOP (DB)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HB32
SN74AHCT32DGVR	Active	Production	TVSOP (DGV)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HB32
SN74AHCT32DGVR.A	Active	Production	TVSOP (DGV)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HB32
SN74AHCT32DR	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHCT32
SN74AHCT32DR.A	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHCT32
SN74AHCT32N	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 125	SN74AHCT32N
SN74AHCT32N.A	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 125	SN74AHCT32N
SN74AHCT32NSR	Active	Production	SOP (NS)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHCT32
SN74AHCT32NSR.A	Active	Production	SOP (NS)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHCT32
SN74AHCT32PW	Obsolete	Production	TSSOP (PW)   14	-	-	Call TI	Call TI	-40 to 125	HB32
SN74AHCT32PWR	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 125	HB32
SN74AHCT32PWR.A	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HB32
SN74AHCT32RGYR	Active	Production	VQFN (RGY)   14	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	HB32
SN74AHCT32RGYR.A	Active	Production	VQFN (RGY)   14	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	HB32

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SNJ54AHCT32FK	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9682601Q2A SNJ54AHCT32FK
SNJ54AHCT32FK.A	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9682601Q2A SNJ54AHCT32FK
SNJ54AHCT32J	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9682601QC A SNJ54AHCT32J
SNJ54AHCT32J.A	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9682601QC A SNJ54AHCT32J
SNJ54AHCT32W	Active	Production	CFP (W)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9682601QD A SNJ54AHCT32W
SNJ54AHCT32W.A	Active	Production	CFP (W)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9682601QD A SNJ54AHCT32W

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

<sup>(4)</sup> **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

---

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

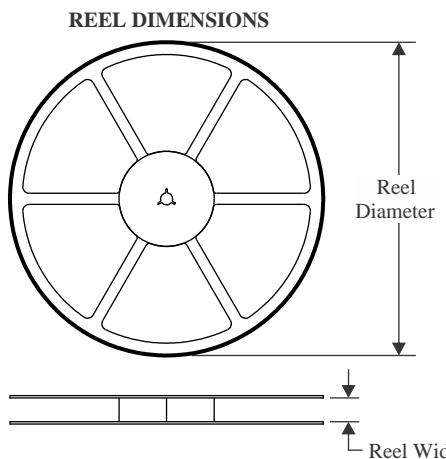
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF SN54AHCT32, SN74AHCT32 :**

- Catalog : [SN74AHCT32](#)
- Automotive : [SN74AHCT32-Q1](#), [SN74AHCT32-Q1](#)
- Enhanced Product : [SN74AHCT32-EP](#), [SN74AHCT32-EP](#)
- Military : [SN54AHCT32](#)

**NOTE: Qualified Version Definitions:**

- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications

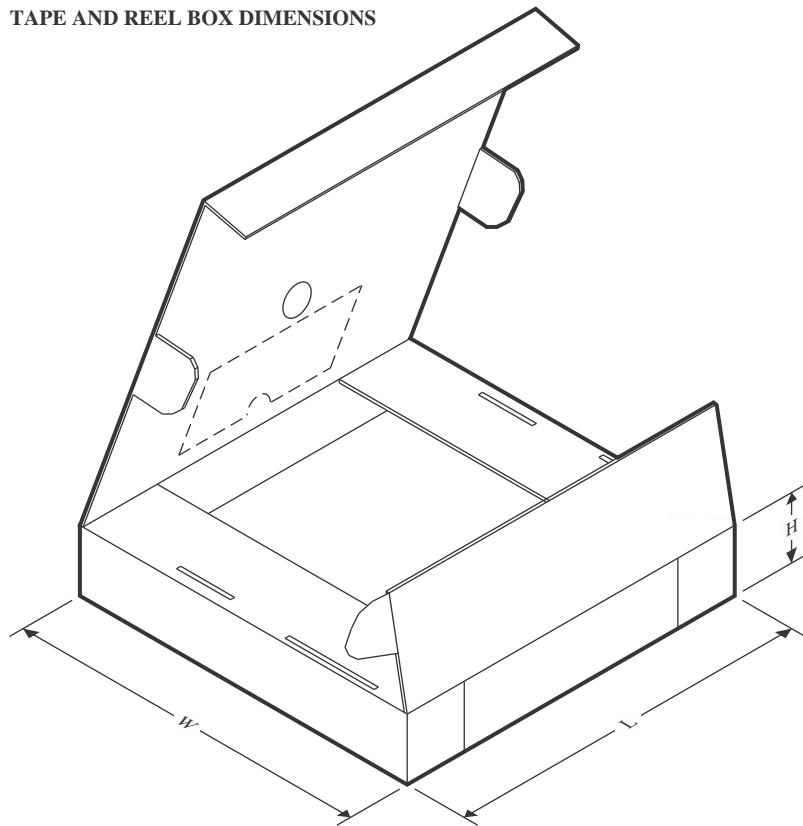
**TAPE AND REEL INFORMATION**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHCT32BQAR	WQFN	BQA	14	3000	180.0	12.4	2.8	3.3	1.1	4.0	12.0	Q1
SN74AHCT32DBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74AHCT32DGVR	TVSOP	DGV	14	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74AHCT32DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AHCT32NSR	SOP	NS	14	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1
SN74AHCT32PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74AHCT32RGYR	VQFN	RGY	14	3000	330.0	12.4	3.75	3.75	1.15	8.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHCT32BQAR	WQFN	BQA	14	3000	210.0	185.0	35.0
SN74AHCT32DBR	SSOP	DB	14	2000	353.0	353.0	32.0
SN74AHCT32DGVR	TVSOP	DGV	14	2000	353.0	353.0	32.0
SN74AHCT32DR	SOIC	D	14	2500	353.0	353.0	32.0
SN74AHCT32NSR	SOP	NS	14	2000	353.0	353.0	32.0
SN74AHCT32PWR	TSSOP	PW	14	2000	353.0	353.0	32.0
SN74AHCT32RGYR	VQFN	RGY	14	3000	353.0	353.0	32.0

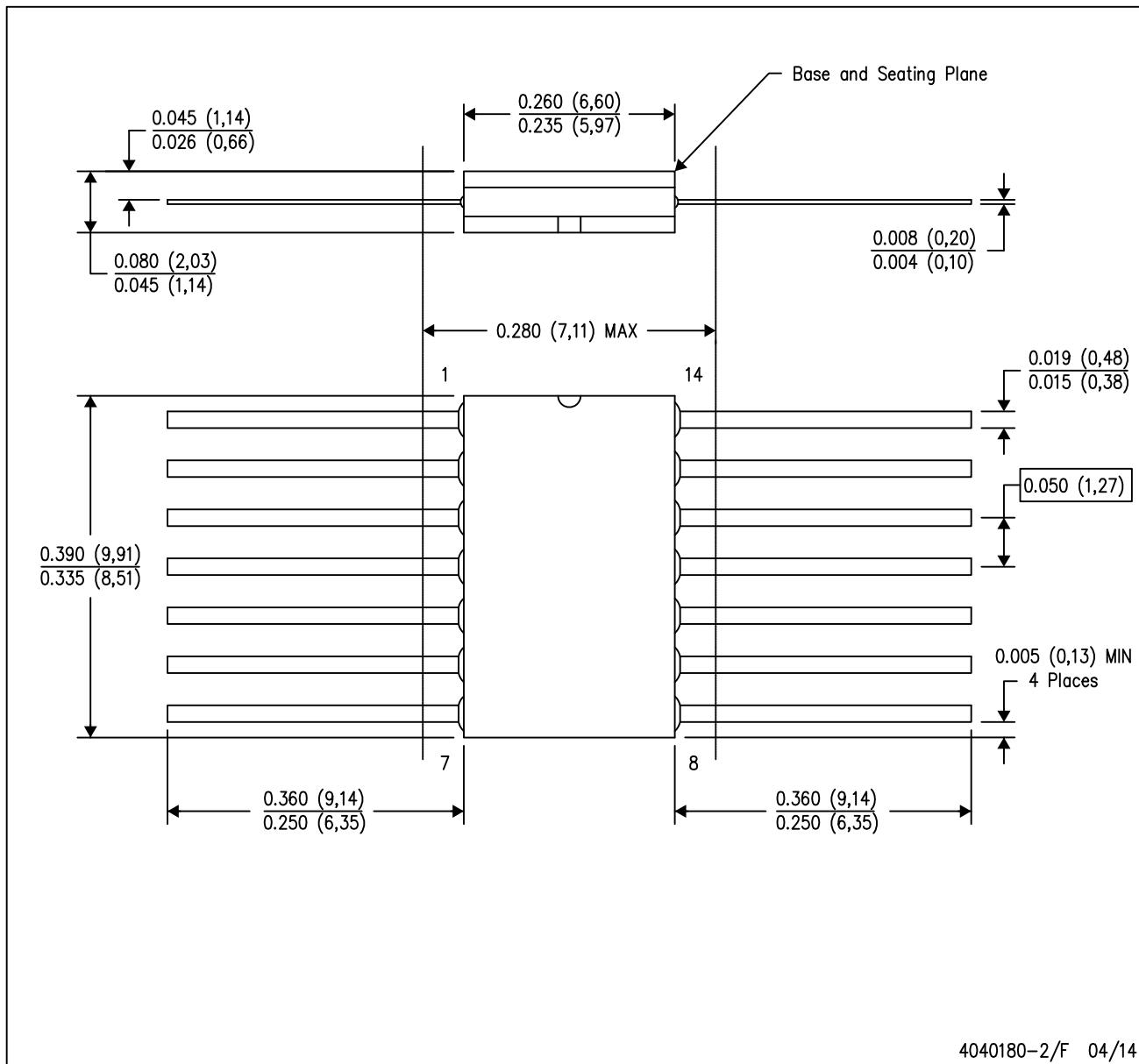
**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T ( $\mu$ m)	B (mm)
5962-9682601Q2A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-9682601QDA	W	CFP	14	25	506.98	26.16	6220	NA
SN74AHCT32N	N	PDIP	14	25	506	13.97	11230	4.32
SN74AHCT32N	N	PDIP	14	25	506	13.97	11230	4.32
SN74AHCT32N.A	N	PDIP	14	25	506	13.97	11230	4.32
SN74AHCT32N.A	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54AHCT32FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54AHCT32FK.A	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54AHCT32W	W	CFP	14	25	506.98	26.16	6220	NA
SNJ54AHCT32W.A	W	CFP	14	25	506.98	26.16	6220	NA

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



4040180-2/F 04/14

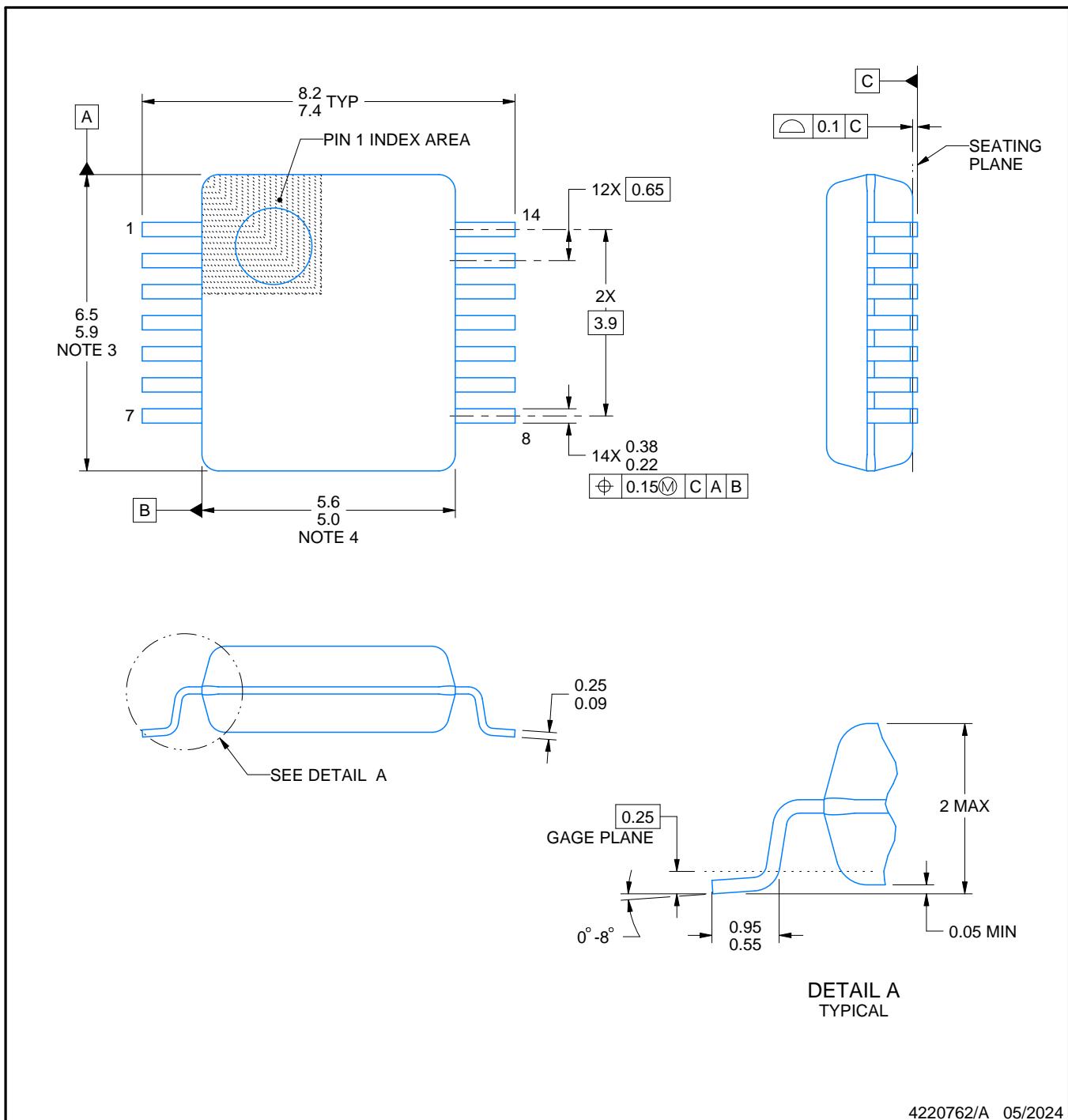
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL-STD 1835 GDFP1-F14

# PACKAGE OUTLINE

## SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



### NOTES:

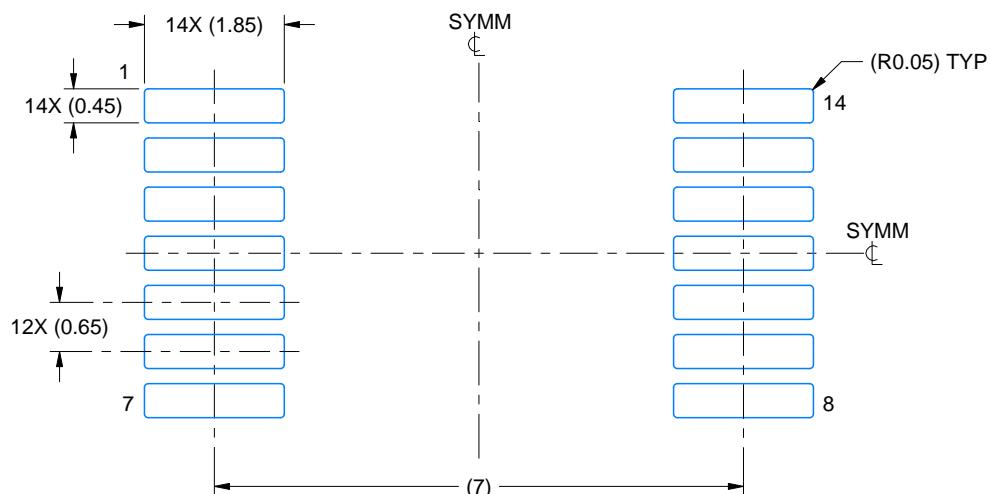
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-150.

## EXAMPLE BOARD LAYOUT

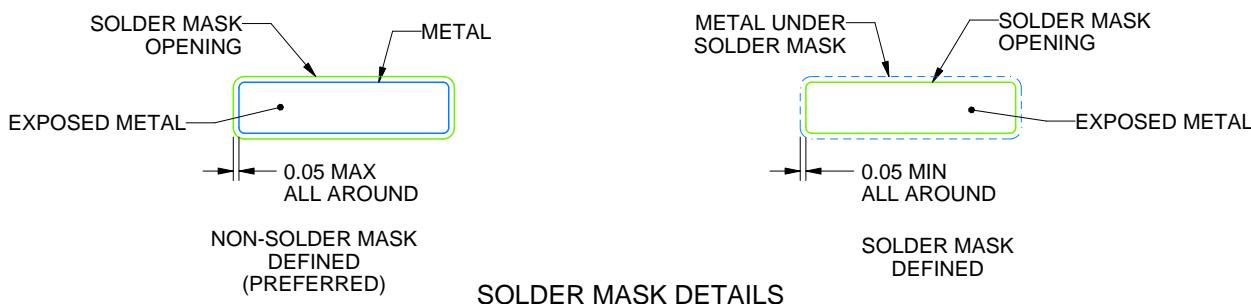
DB0014A

## SSOP - 2 mm max height

## SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4220762/A 05/2024

#### NOTES: (continued)

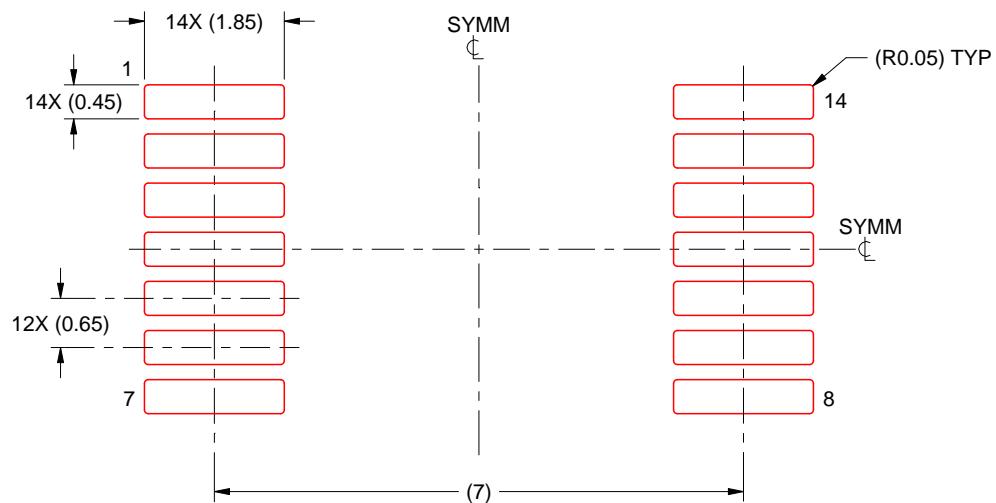
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DB0014A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220762/A 05/2024

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

# GENERIC PACKAGE VIEW

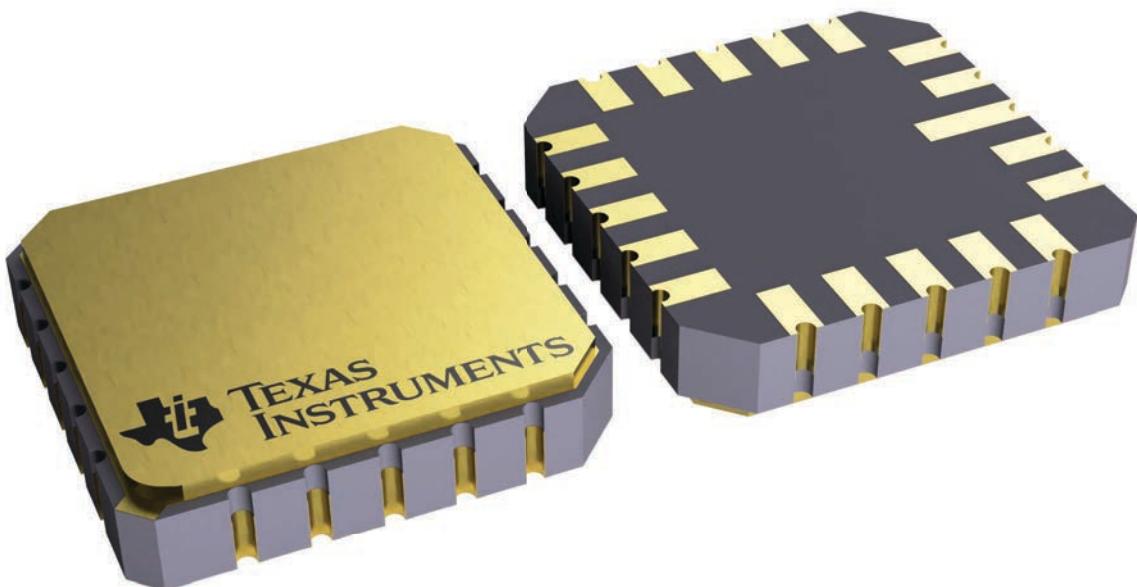
**FK 20**

**LCCC - 2.03 mm max height**

**8.89 x 8.89, 1.27 mm pitch**

**LEADLESS CERAMIC CHIP CARRIER**

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



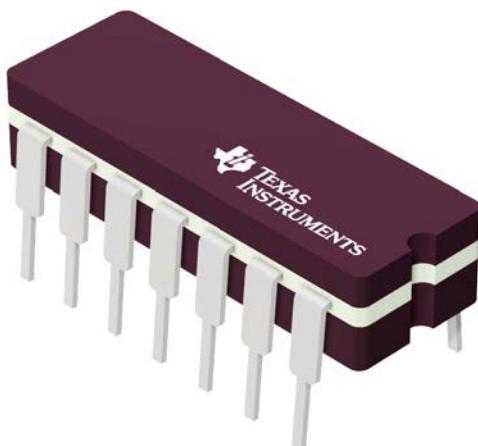
4229370VA\

# GENERIC PACKAGE VIEW

**J 14**

**CDIP - 5.08 mm max height**

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4040083-5/G

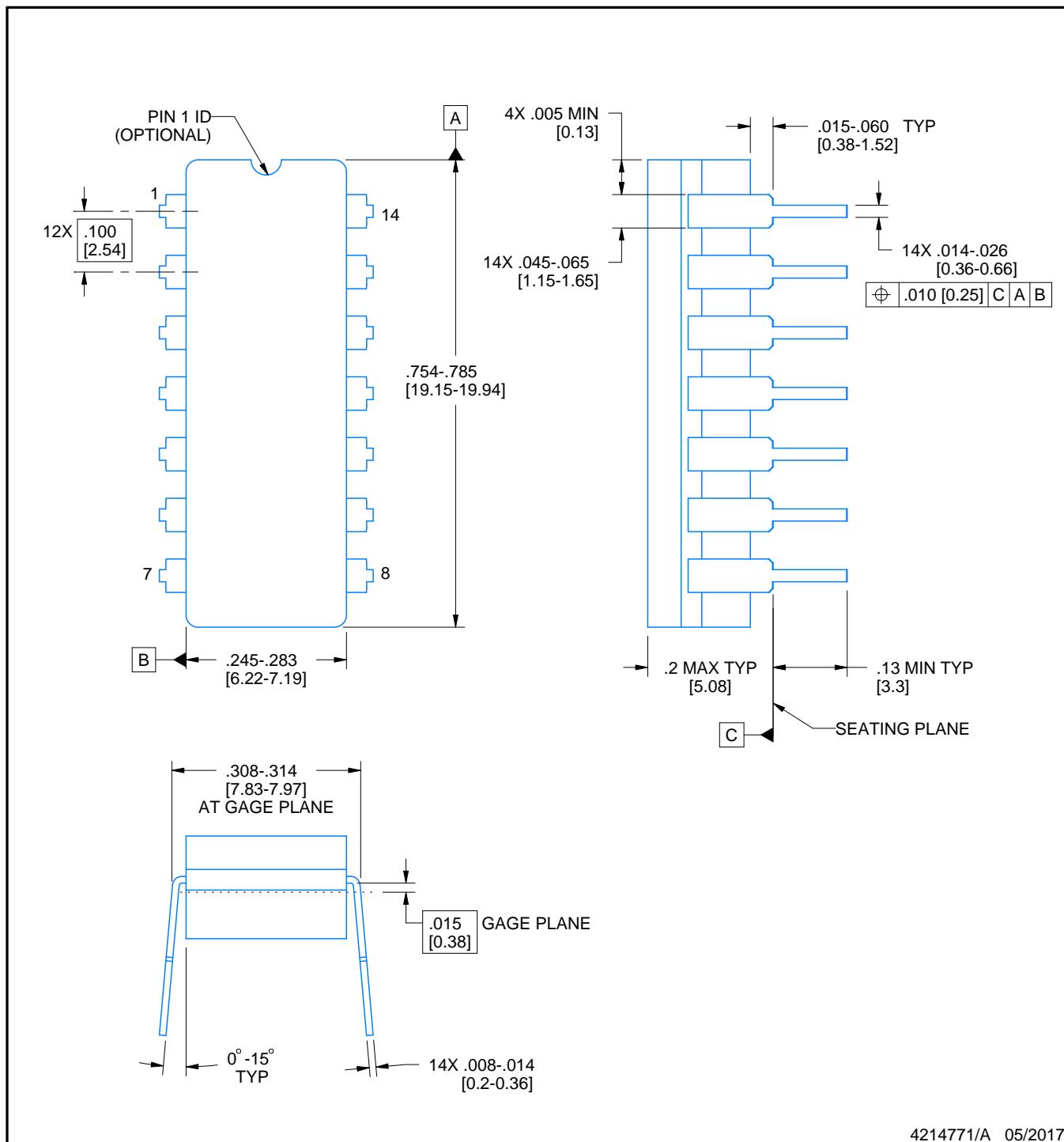


# PACKAGE OUTLINE

J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



4214771/A 05/2017

## NOTES:

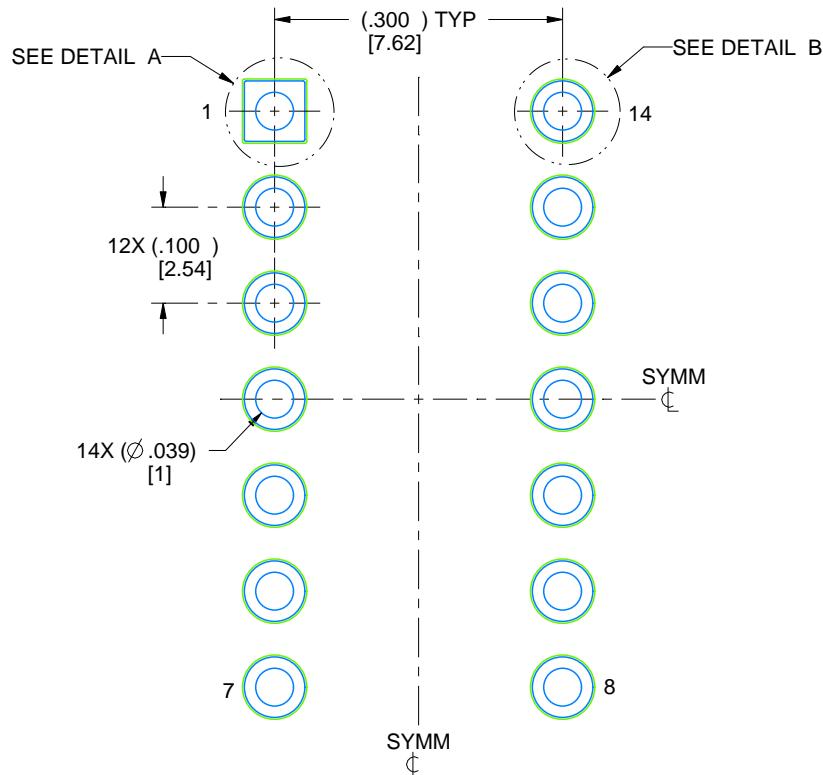
1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

# EXAMPLE BOARD LAYOUT

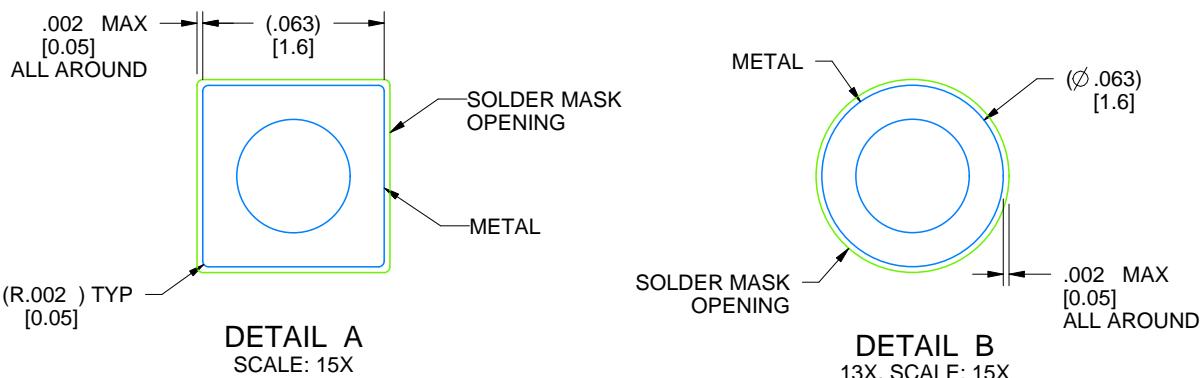
J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



LAND PATTERN EXAMPLE  
NON-SOLDER MASK DEFINED  
SCALE: 5X

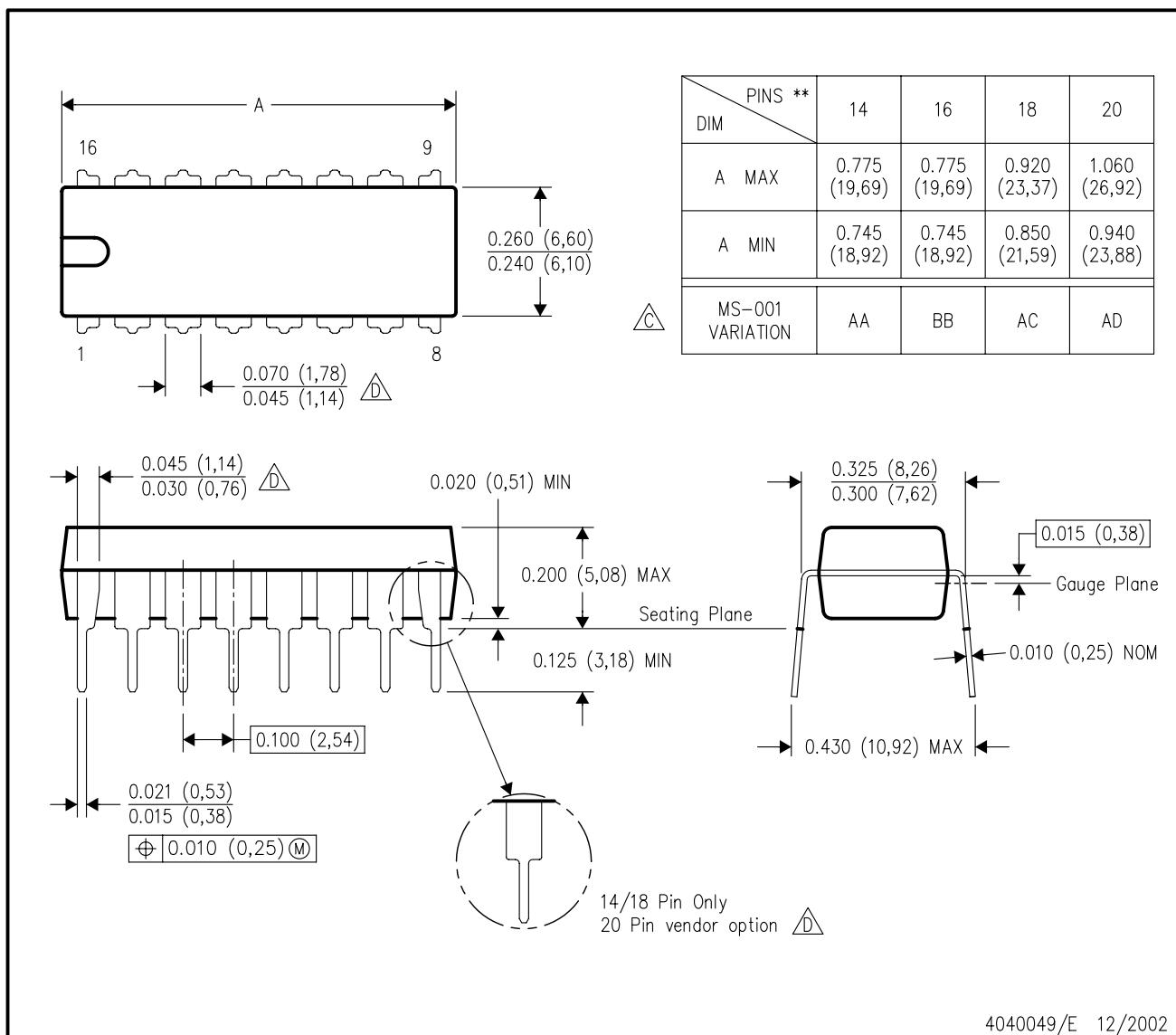


4214771/A 05/2017

## N (R-PDIP-T\*\*)

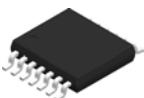
16 PINS SHOWN

## PLASTIC DUAL-IN-LINE PACKAGE



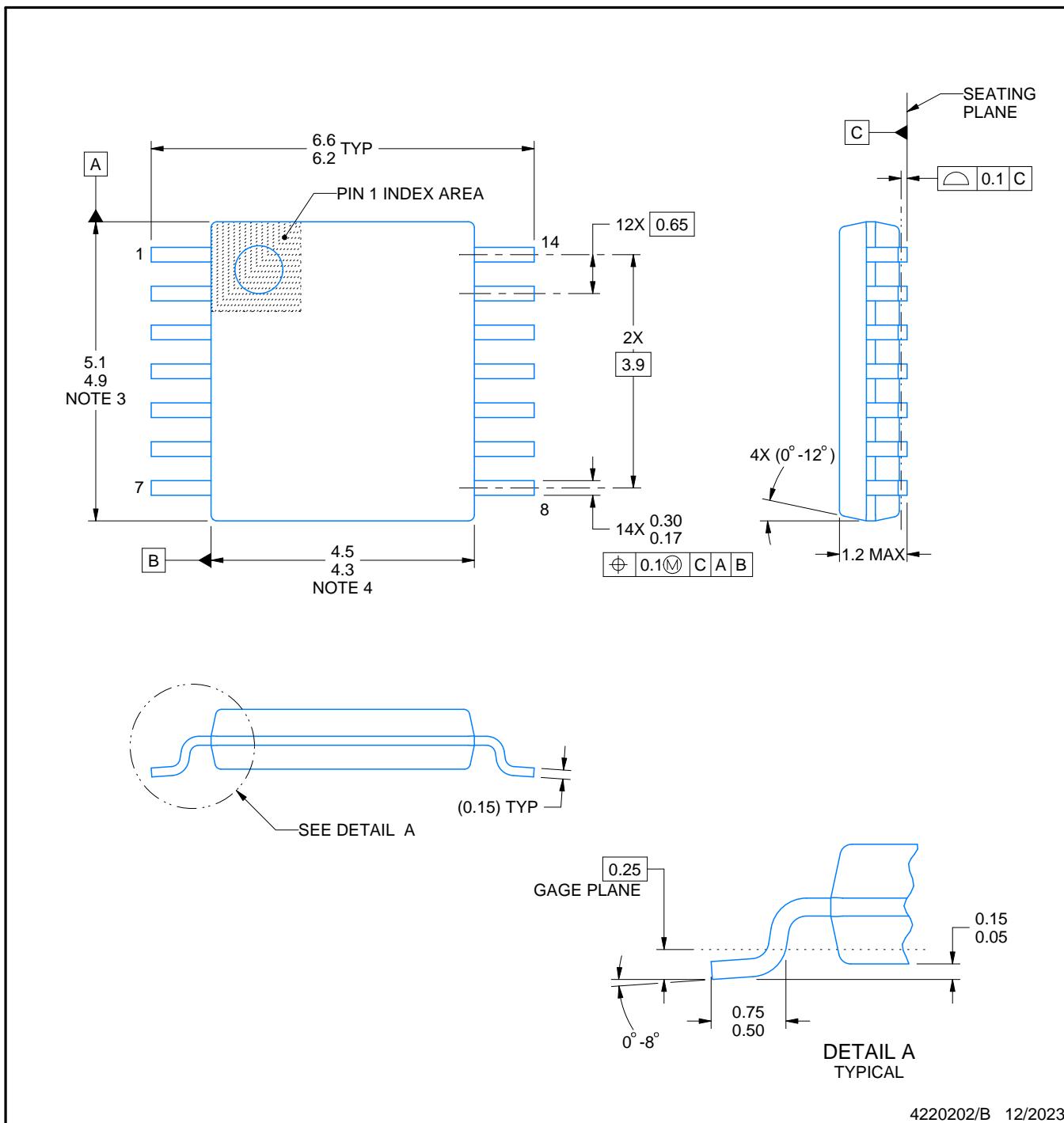
# PACKAGE OUTLINE

PW0014A



TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



## NOTES:

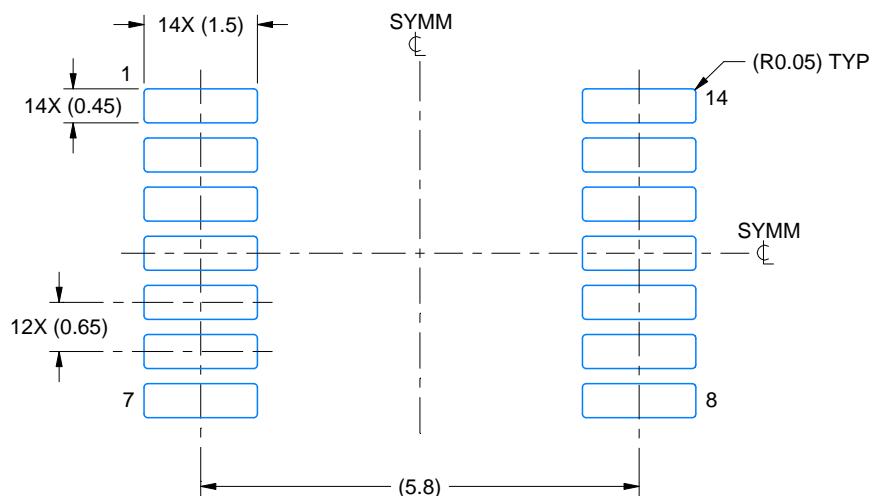
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

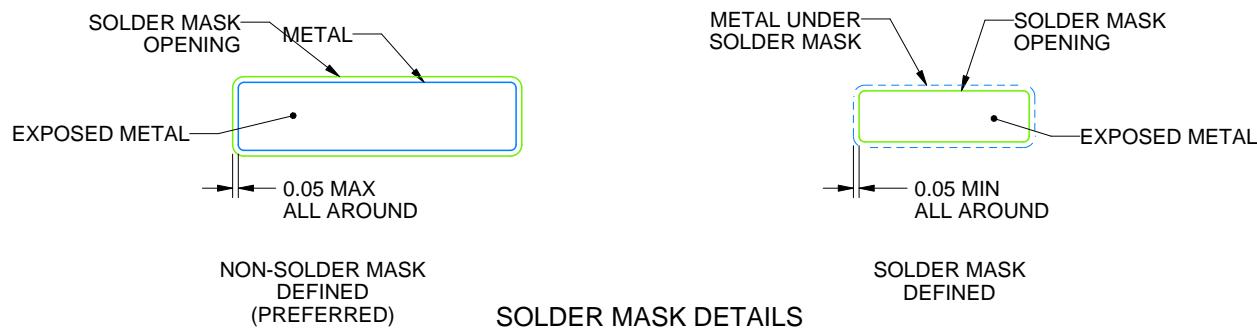
PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4220202/B 12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

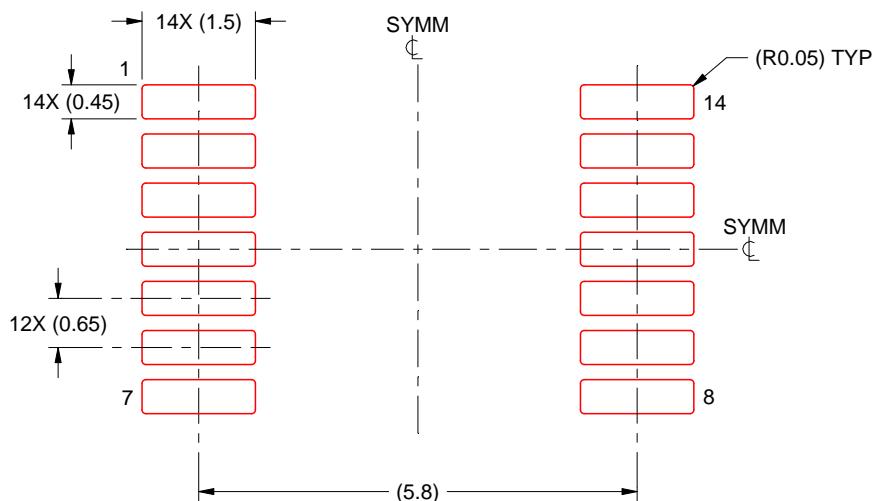
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220202/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

## GENERIC PACKAGE VIEW

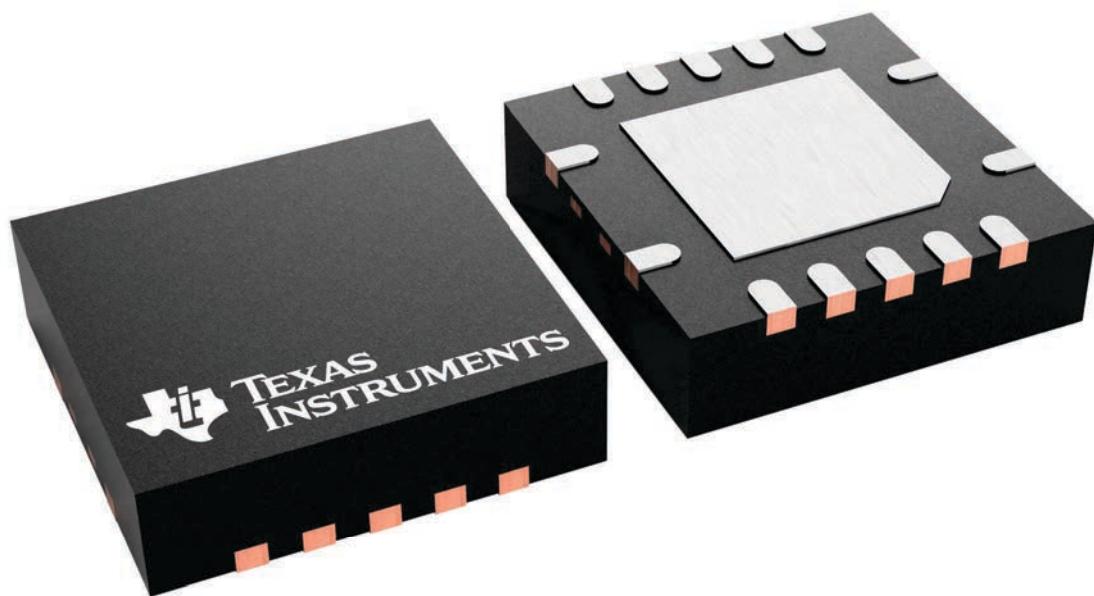
**RGY 14**

**VQFN - 1 mm max height**

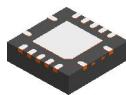
**3.5 x 3.5, 0.5 mm pitch**

**PLASTIC QUAD FLATPACK - NO LEAD**

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



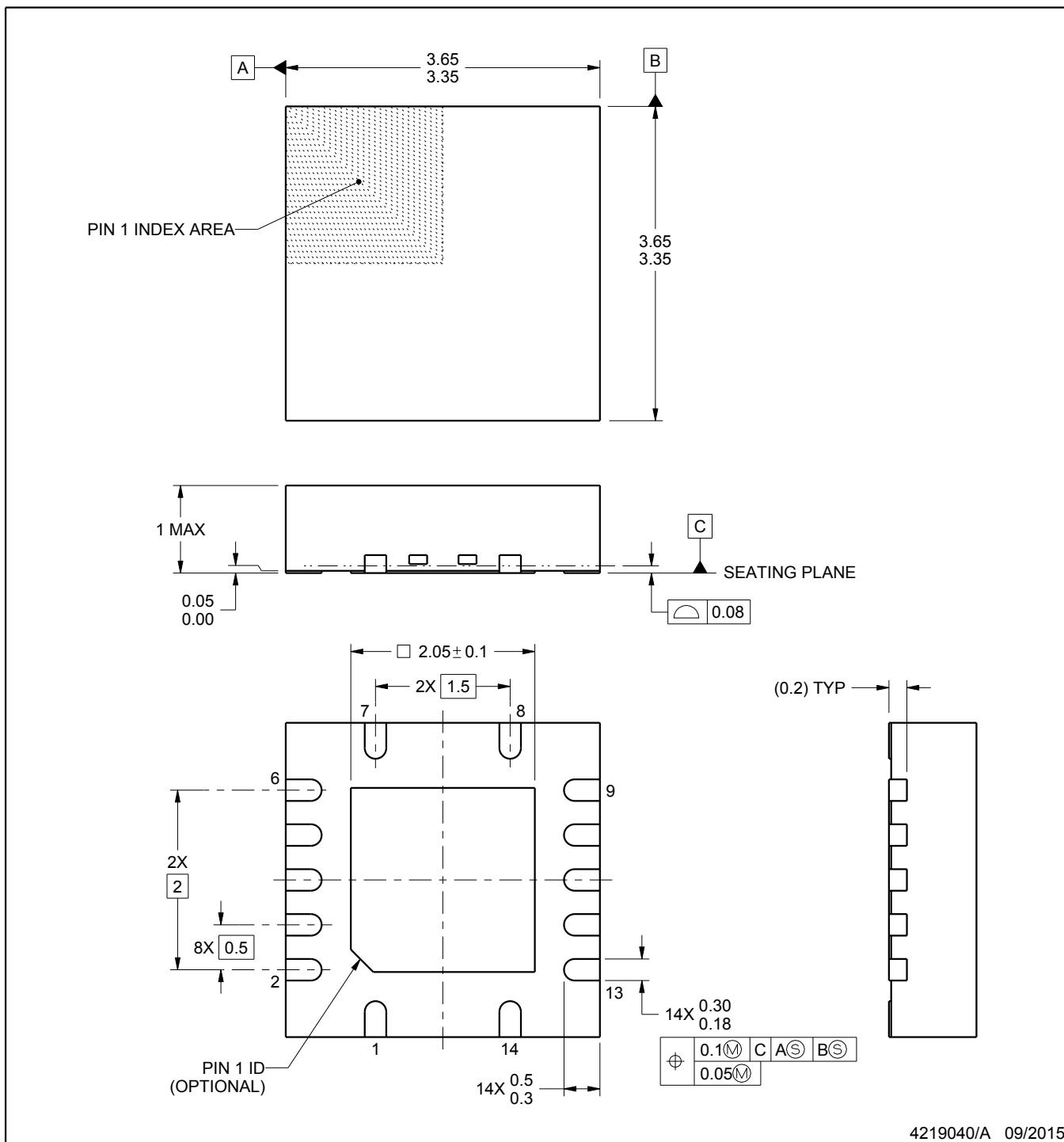
4231541/A



# PACKAGE OUTLINE

## VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



### NOTES:

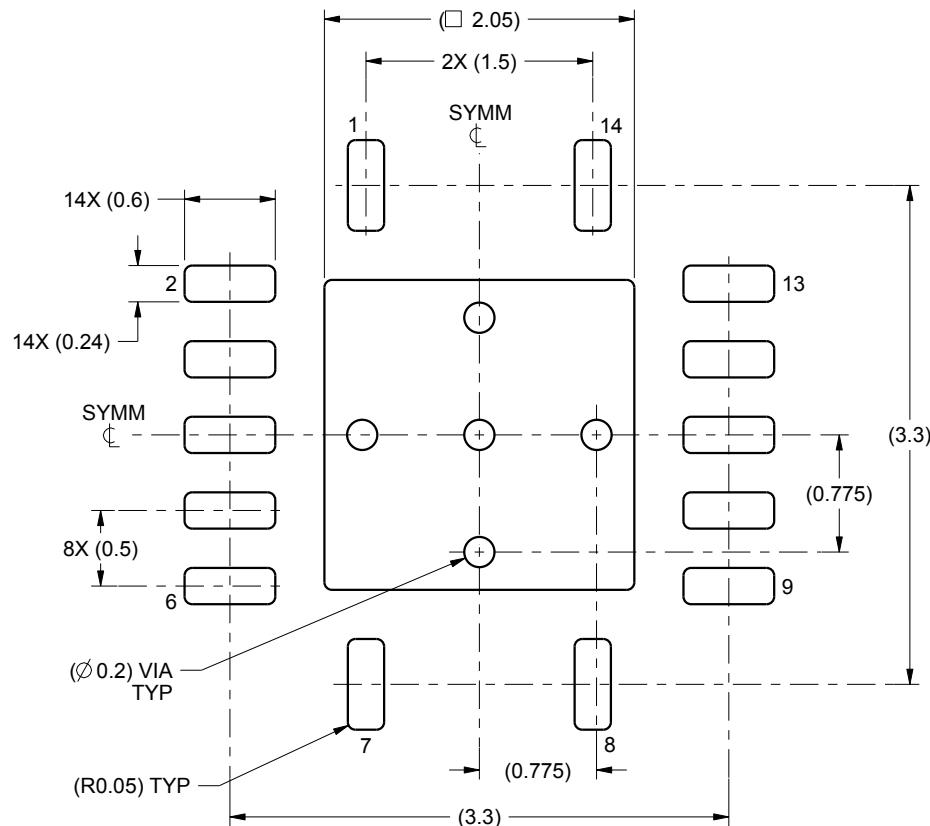
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

# EXAMPLE BOARD LAYOUT

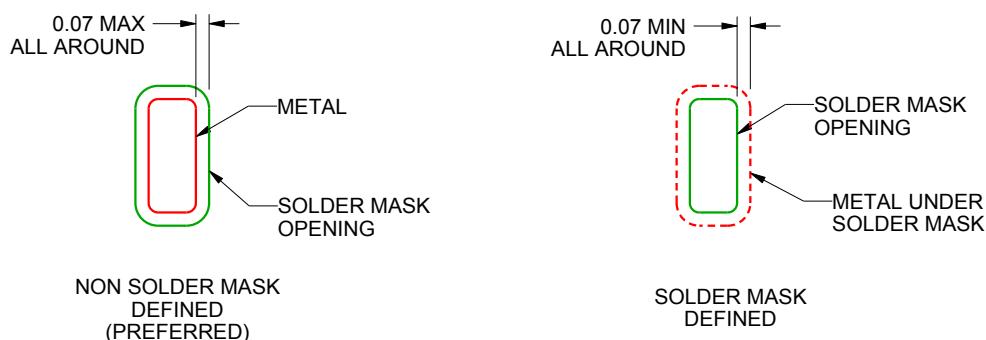
RGY0014A

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE  
SCALE:20X



SOLDER MASK DETAILS

4219040/A 09/2015

NOTES: (continued)

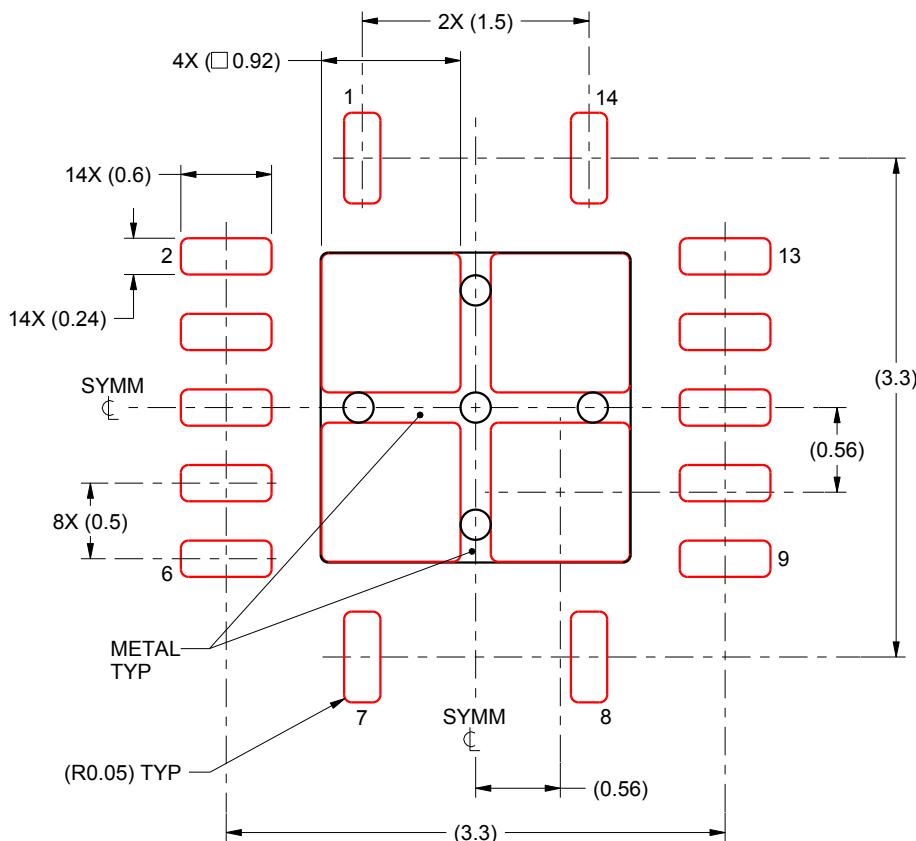
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).

# EXAMPLE STENCIL DESIGN

RGY0014A

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD  
80% PRINTED SOLDER COVERAGE BY AREA  
SCALE:20X

4219040/A 09/2015

NOTES: (continued)

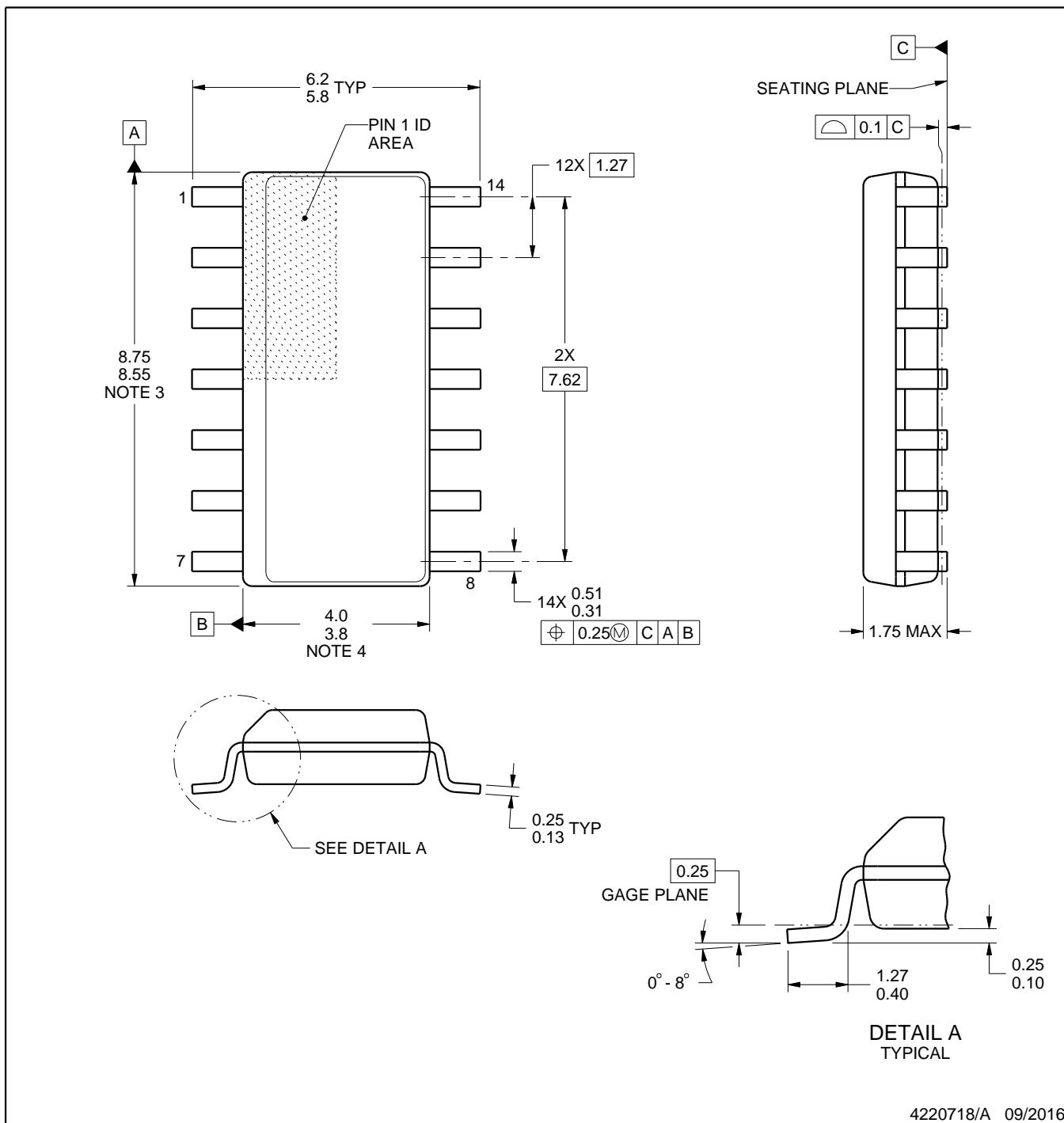
5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

# PACKAGE OUTLINE

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



## NOTES:

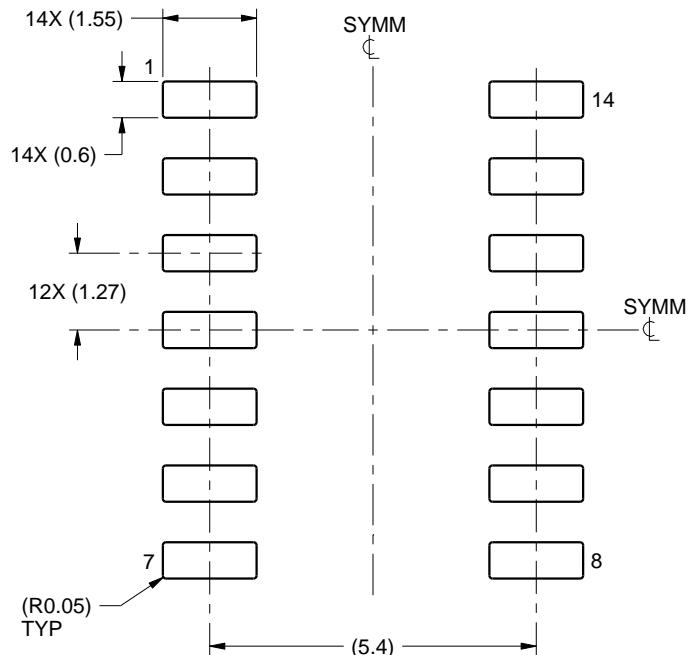
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.

# EXAMPLE BOARD LAYOUT

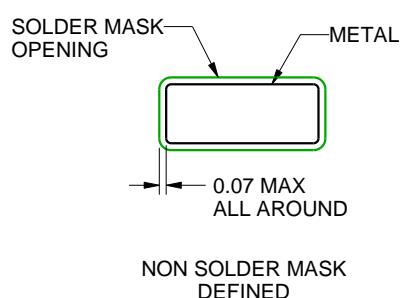
D0014A

SOIC - 1.75 mm max height

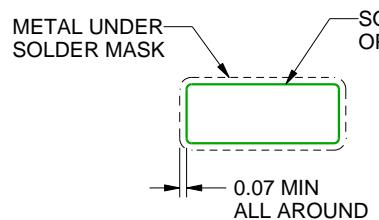
SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE  
SCALE:8X



NON SOLDER MASK  
DEFINED



SOLDER MASK  
DEFINED

SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

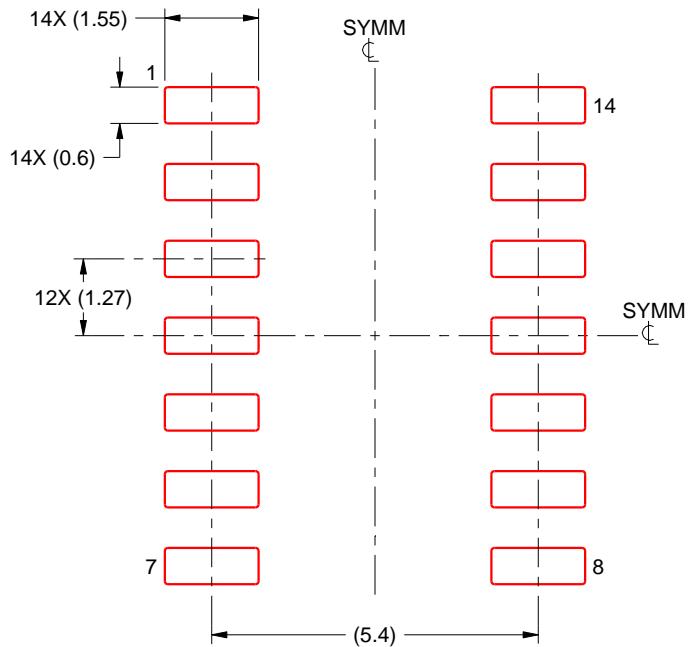
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:8X

4220718/A 09/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

## GENERIC PACKAGE VIEW

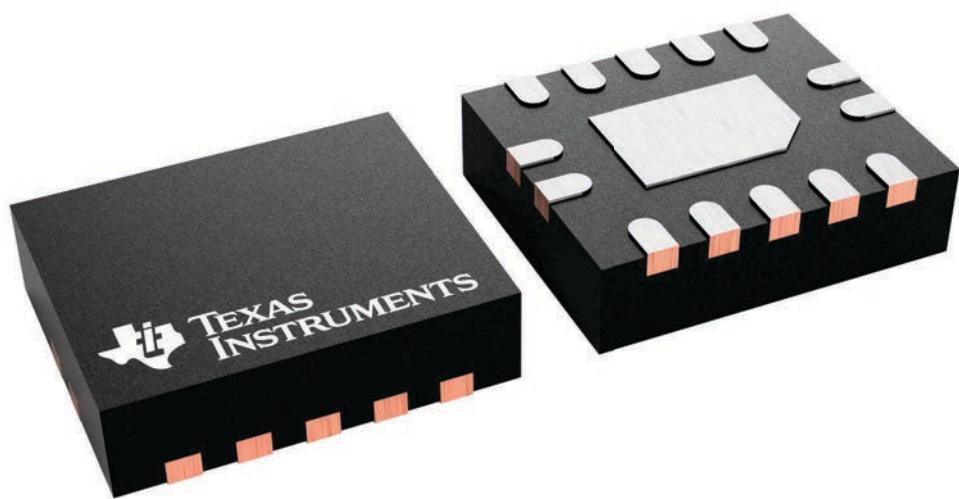
**BQA 14**

**WQFN - 0.8 mm max height**

**2.5 x 3, 0.5 mm pitch**

**PLASTIC QUAD FLATPACK - NO LEAD**

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



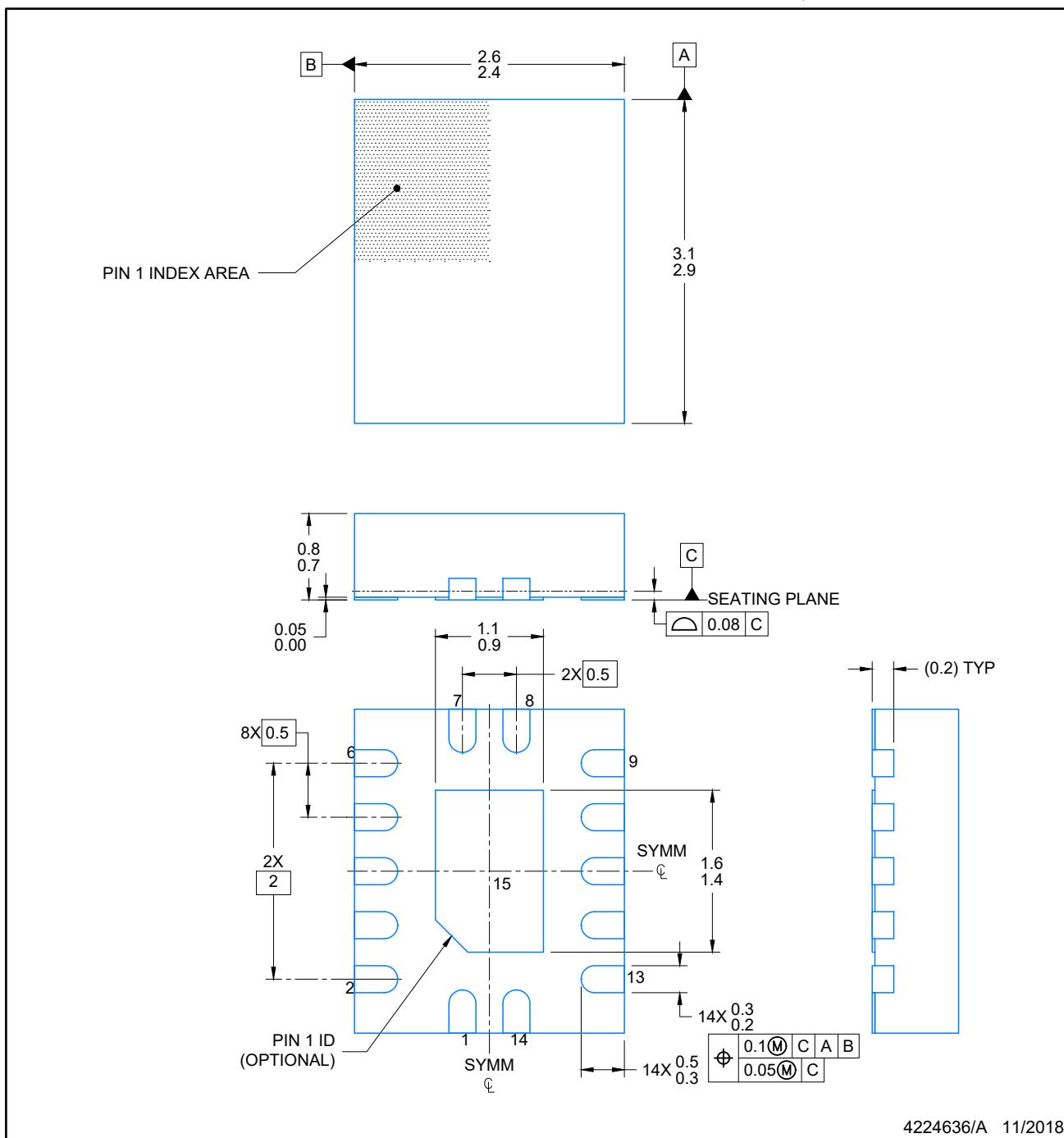
4227145/A

# PACKAGE OUTLINE

## WQFN - 0.8 mm max height

BQA0014A

PLASTIC QUAD FLAT PACK-NO LEAD



### NOTES:

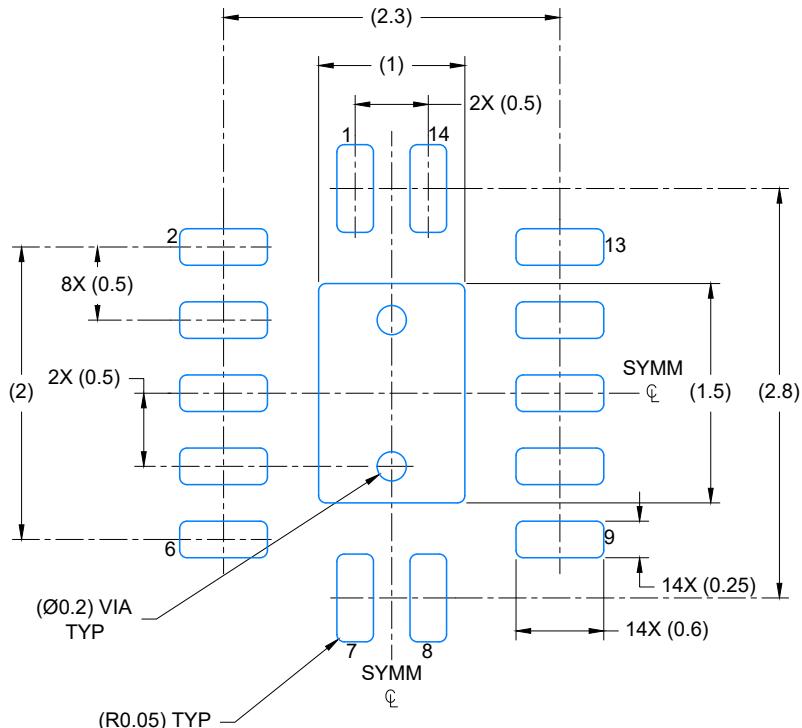
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for optimal thermal and mechanical performance.

## EXAMPLE BOARD LAYOUT

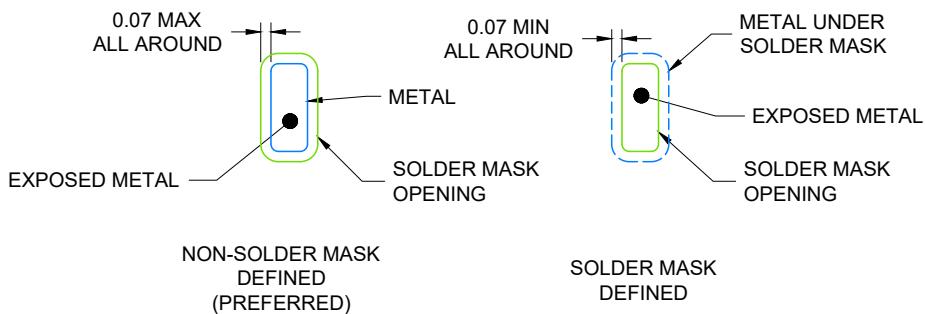
**BQA0014A**

## **WQFN - 0.8 mm max height**

**PLASTIC QUAD FLAT PACK-NO LEAD**



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 20X



4224636/A 11/2018

#### NOTES: (continued)

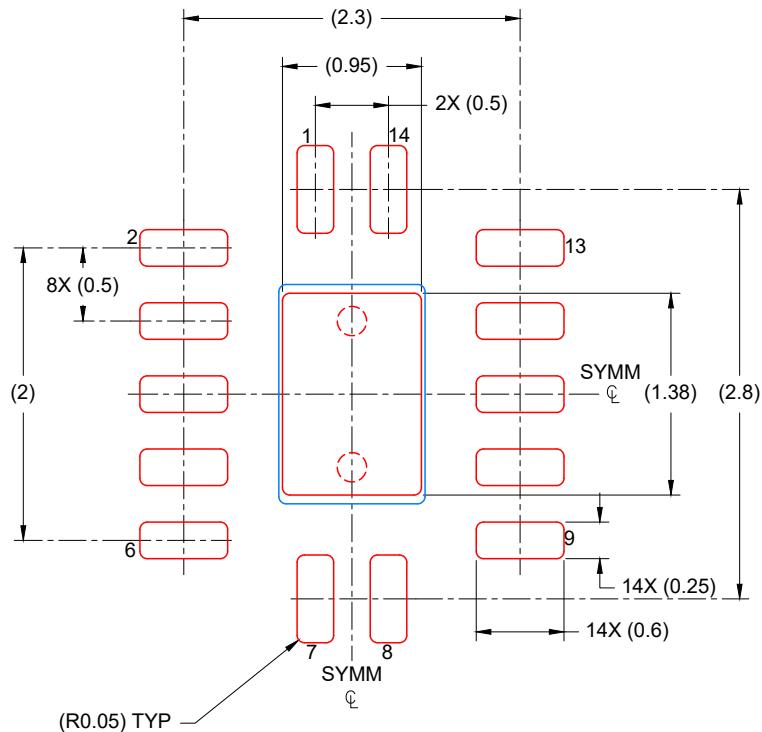
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

# EXAMPLE STENCIL DESIGN

BQA0014A

WQFN - 0.8 mm max height

PLASTIC QUAD FLAT PACK-NO LEAD



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD  
88% PRINTED COVERAGE BY AREA  
SCALE: 20X

4224636/A 11/2018

NOTES: (continued)

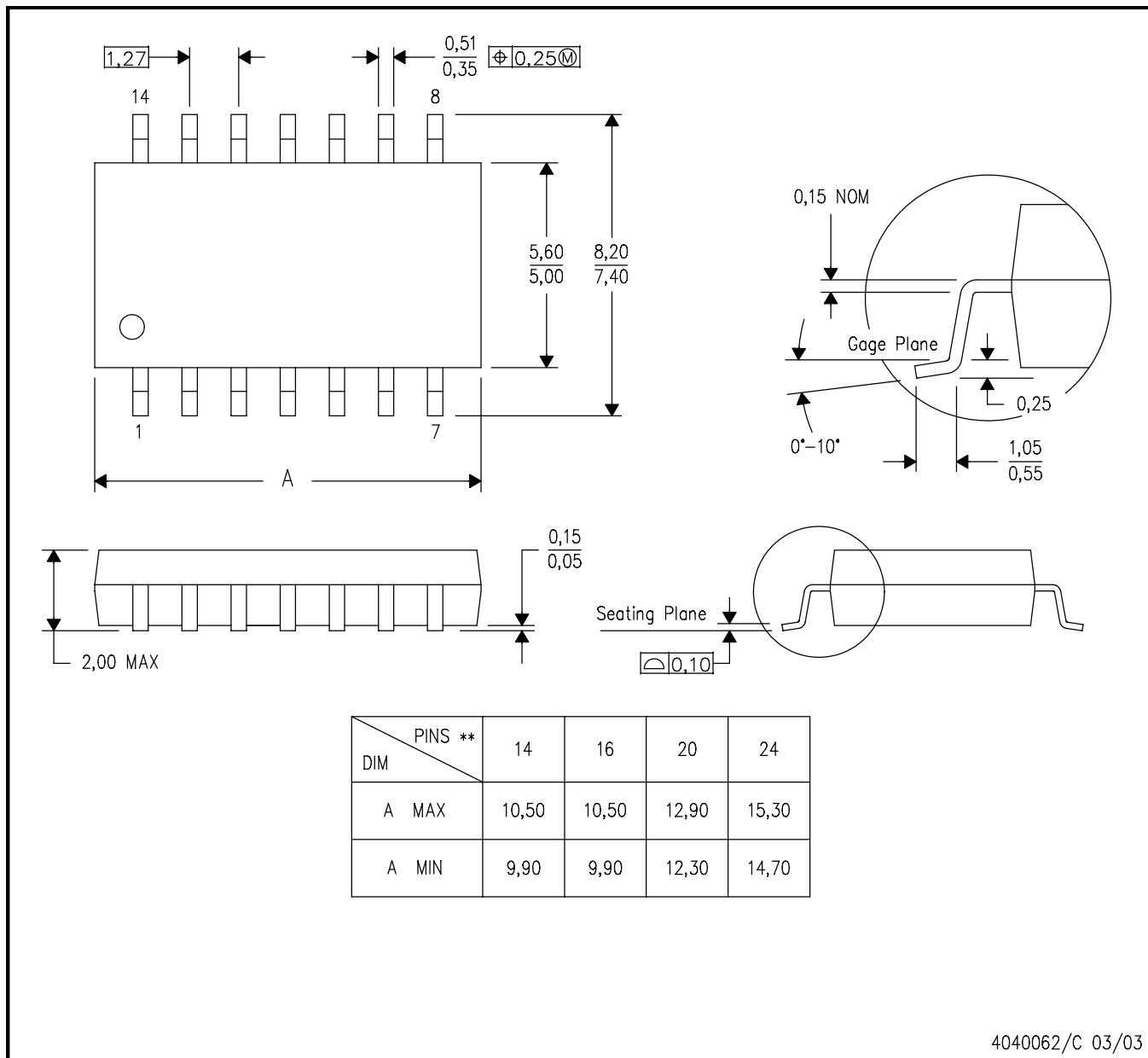
6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

## MECHANICAL DATA

**NS (R-PDSO-G\*\*)**

## PLASTIC SMALL-OUTLINE PACKAGE

**14-PINS SHOWN**



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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